

Please amend the application as follows:

In the Claims:

Please amend the claims as follows:

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1. (amended) A die pad configuration for an integrated circuit having an integrated circuit die, the die pad configuration comprising:
four separate die pad regions, each of said die pad regions under one of the four corners of said integrated circuit die.
 2. (cancelled)
 3. (amended) The die pad configuration of claim 1 wherein the ratio of the total area of the four die pad regions to the die area is in the range of about 0.3 to about 0.5.
 4. (amended) The die pad configuration of claim 3 wherein the ratio is about 0.32.
 5. (cancelled)
 6. (cancelled)
 7. (cancelled)
 8. (amended) A die pad for an integrated circuit having an integrated circuit die, the die pad comprising a support portion for supporting the integrated circuit die, the support portion supporting substantially all of said integrated circuit die, except that corner regions of said die are not supported by said support portion.

9. (amended) The die pad of claim 8, wherein the ratio of the area of the support portion of the die pad to the area of the die is in the range of about 0.3 to about 0.5.

10. (cancelled)

11. (cancelled)

12. (cancelled)

cont'd
B1 [Please add the following new claims:]

13. (new) A die pad configuration for an integrated circuit including a rectangular integrated circuit die having two long opposing edges and two short opposing edges, the die pad configuration comprising:

two separate die pad regions, each of said die pad regions under one of said two long opposing edges of said integrated circuit die.

14. (new) The die pad configuration of claim 13 wherein the ratio of the total area of the two die pad regions is in the range of about 0.40 to about 0.50.

15. (new) The die pad configuration of claim 14 wherein the ratio is about 0.42.

REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.